



查询SI1016X供应商

捷多邦，专业PCB打样工厂，24小时加急出货

Complementary N- and P-Channel 20-V (D-S) MOSFET

PRODUCT SUMMARY

	V_{DS} (V)	$r_{DS(on)}$ (Ω)	I_D (mA)
N-Channel	20	0.70 @ $V_{GS} = 4.5$ V	600
		0.85 @ $V_{GS} = 2.5$ V	500
		1.25 @ $V_{GS} = 1.8$ V	350
P-Channel	-20	1.2 @ $V_{GS} = -4.5$ V	-400
		1.6 @ $V_{GS} = -2.5$ V	-300
		2.7 @ $V_{GS} = -1.8$ V	-150

TrenchFET®

MOSFETs
1.8-V RatedESD Protected
2000 V

FEATURES

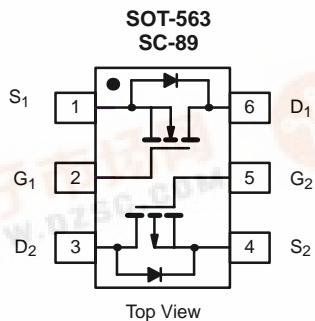
- Very Small Footprint
- High-Side Switching
- Low On-Resistance:
N-Channel, 0.7 Ω
P-Channel, 1.2 Ω
- Low Threshold: ± 0.8 V (typ)
- Fast Switching Speed: 14 ns
- 1.8-V Operation
- Gate-Source ESD Protection

BENEFITS

- Ease in Driving Switches
- Low Offset (Error) Voltage
- Low-Voltage Operation
- High-Speed Circuits
- Low Battery Voltage Operation

APPLICATIONS

- Replace Digital Transistor, Level-Shifter
- Battery Operated Systems
- Power Supply Converter Circuits
- Load/Power Switching Cell Phones, Pagers



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ UNLESS OTHERWISE NOTED)

Parameter	Symbol	N-Channel		P-Channel		Unit
		5 secs	Steady State	5 secs	Steady State	
Drain-Source Voltage	V_{DS}	20		-20		V
Gate-Source Voltage	V_{GS}		± 6			
Continuous Drain Current ($T_J = 150^\circ\text{C}$) ^a	I_D	515	485	-390	-370	mA
		370	350	-280	-265	
Pulsed Drain Current ^b	I_{DM}	650		-650		
Continuous Source Current (Diode Conduction) ^a	I_S	450	380	-450	-380	
Maximum Power Dissipation ^a	P_D	280	250	280	250	mW
		145	130	145	130	
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55 to 150				°C
Gate-Source ESD Rating (HBM, Method 3015)	ESD	2000				V

^a Surface Mounted on FR4 Board.^b Pulse width limited by maximum junction temperature.

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New Product

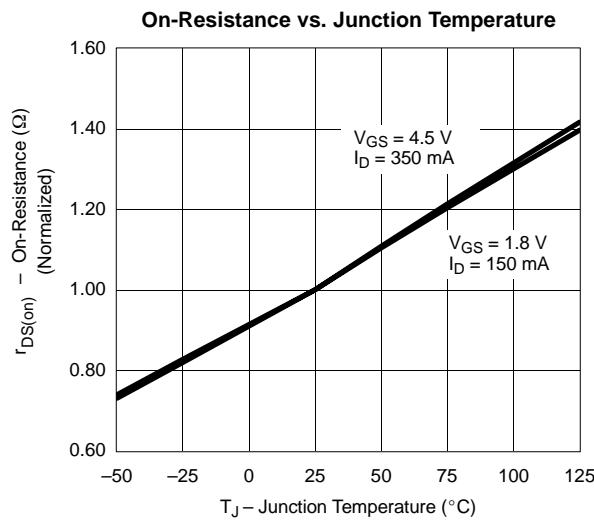
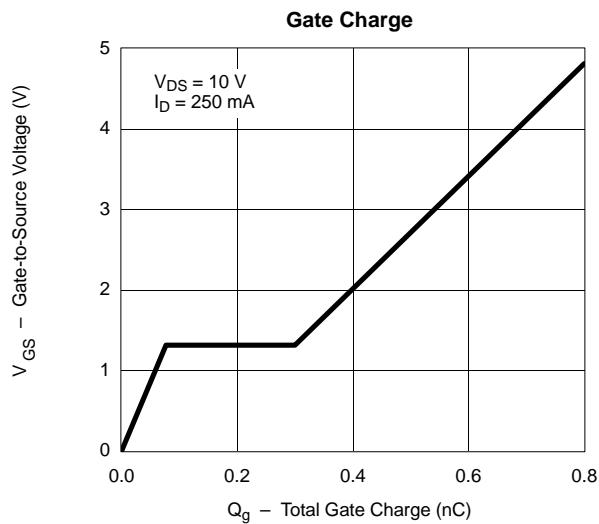
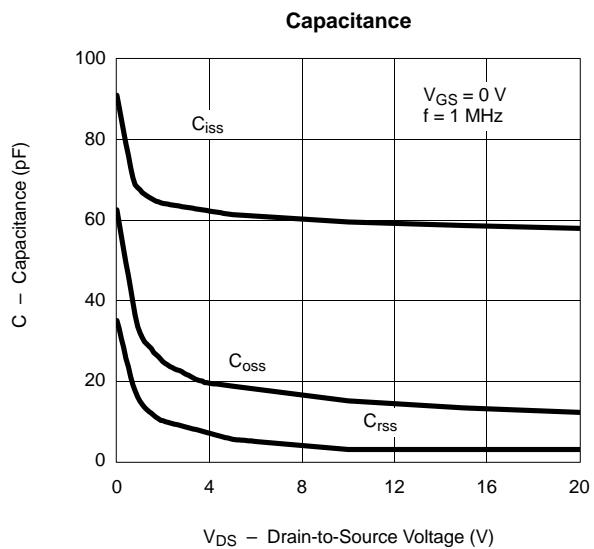
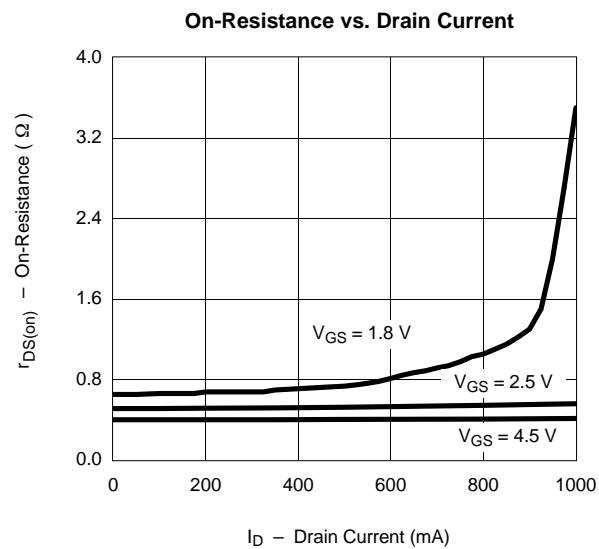
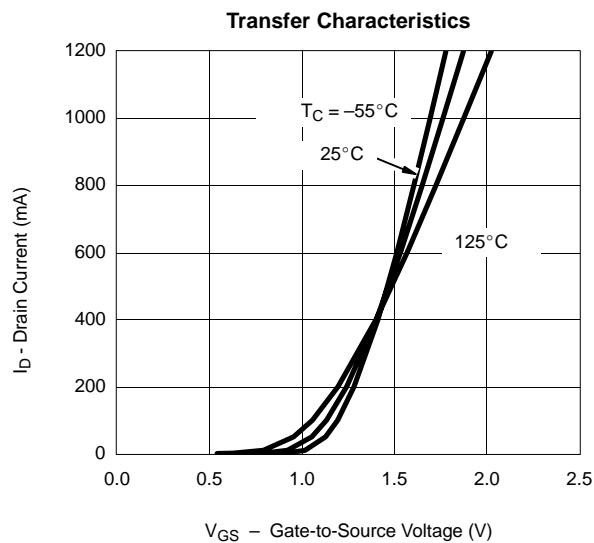
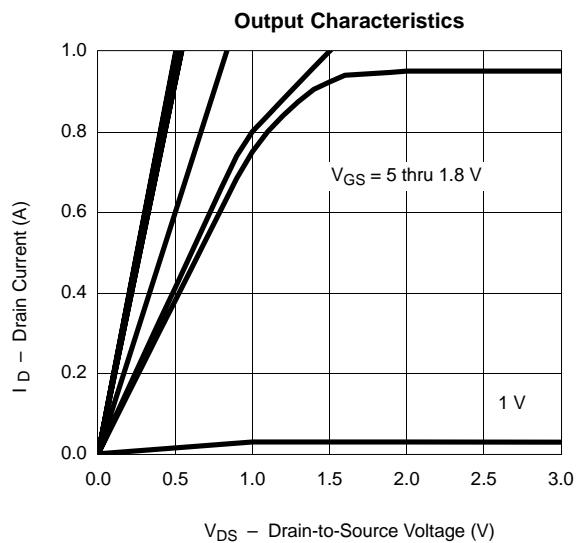


SPECIFICATIONS ($T_J = 25^\circ\text{C}$ UNLESS OTHERWISE NOTED)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Static						
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	N-Ch	0.45		
		$V_{DS} = V_{GS}, I_D = -250 \mu\text{A}$	P-Ch	-0.45		V
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 4.5 \text{ V}$	N-Ch P-Ch	± 0.5 ± 1.0	± 1.0 ± 2.0	μA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 16 \text{ V}, V_{GS} = 0 \text{ V}$	N-Ch	0.3	100	nA
		$V_{DS} = -16 \text{ V}, V_{GS} = 0 \text{ V}$	P-Ch	-0.3	-100	nA
		$V_{DS} = 16 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 85^\circ\text{C}$	N-Ch		5	μA
		$V_{DS} = -16 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 85^\circ\text{C}$	P-Ch		-5	μA
On-State Drain Current ^a	$I_{D(\text{on})}$	$V_{DS} = 5 \text{ V}, V_{GS} = 4.5 \text{ V}$	N-Ch	700		
		$V_{DS} = -5 \text{ V}, V_{GS} = -4.5 \text{ V}$	P-Ch	-700		mA
Drain-Source On-State Resistance ^a	$r_{DS(\text{on})}$	$V_{GS} = 4.5 \text{ V}, I_D = 600 \text{ mA}$	N-Ch	0.41	0.70	Ω
		$V_{GS} = -4.5 \text{ V}, I_D = -350 \text{ mA}$	P-Ch	0.80	1.2	
		$V_{GS} = 2.5 \text{ V}, I_D = 500 \text{ mA}$	N-Ch	0.53	0.85	
		$V_{GS} = -2.5 \text{ V}, I_D = -300 \text{ mA}$	P-Ch	1.20	1.6	
		$V_{GS} = 1.8 \text{ V}, I_D = 350 \text{ mA}$	N-Ch	0.70	1.25	
		$V_{GS} = -1.8 \text{ V}, I_D = -150 \text{ mA}$	P-Ch	1.80	2.7	
Forward Transconductance ^a	g_{fs}	$V_{DS} = 10 \text{ V}, I_D = 400 \text{ mA}$	N-Ch	1.0		
		$V_{DS} = -10 \text{ V}, I_D = -250 \text{ mA}$	P-Ch	0.4		s
Diode Forward Voltage ^a	V_{SD}	$I_S = 150 \text{ mA}, V_{GS} = 0 \text{ V}$	N-Ch	0.8	1.2	V
		$I_S = -150 \text{ mA}, V_{GS} = 0 \text{ V}$	P-Ch	-0.8	-1.2	
Dynamic^b						
Total Gate Charge	Q_g	N-Channel $V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 250 \text{ mA}$ P-Channel $V_{DS} = -10 \text{ V}, V_{GS} = -4.5 \text{ V}, I_D = -250 \text{ mA}$	N-Ch		750	pC
Gate-Source Charge	Q_{gs}		P-Ch		1500	
Gate-Drain Charge	Q_{gd}		N-Ch		75	
Turn-On Time	t_{ON}		P-Ch		150	
Turn-Off Time	t_{OFF}		N-Ch		225	ns
			P-Ch		450	
		N-Channel $V_{DD} = 10 \text{ V}, R_L = 47 \Omega$ $I_D \approx 200 \text{ mA}, V_{GEN} = 4.5 \text{ V}, R_G = 10 \Omega$ P-Channel $V_{DD} = -10 \text{ V}, R_L = 47 \Omega$ $I_D \approx -200 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_G = 10 \Omega$	N-Ch		5	ns
			P-Ch		5	
			N-Ch		25	
			P-Ch		35	

Notes

- a. Pulse test; pulse width $\leq 300 \mu\text{s}$, duty cycle $\leq 2\%$.
- b. Guaranteed by design, not subject to production testing.

TYPICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ UNLESS NOTED)
N-CHANNEL


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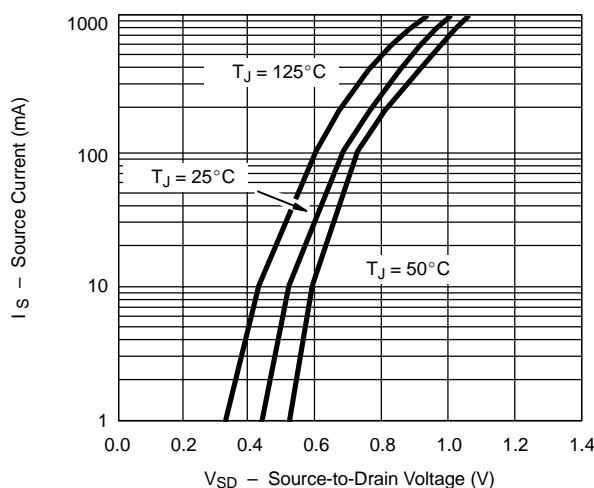
New Product



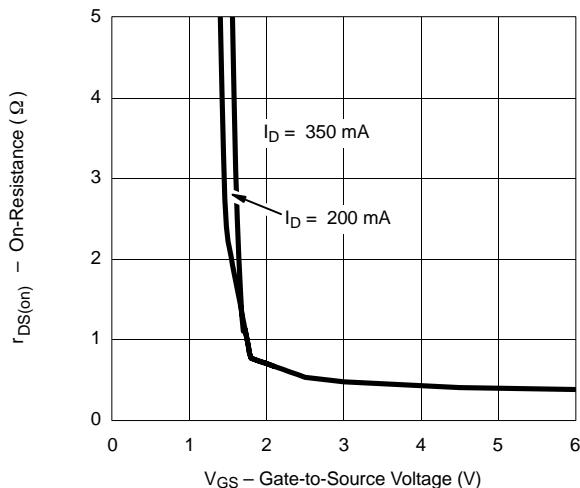
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N-CHANNEL

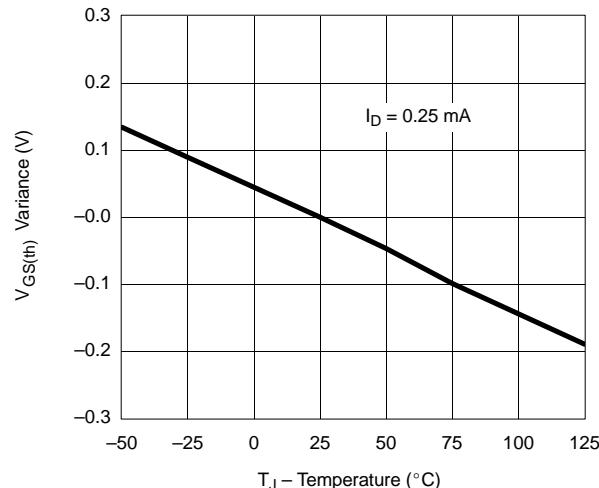
Source-Drain Diode Forward Voltage



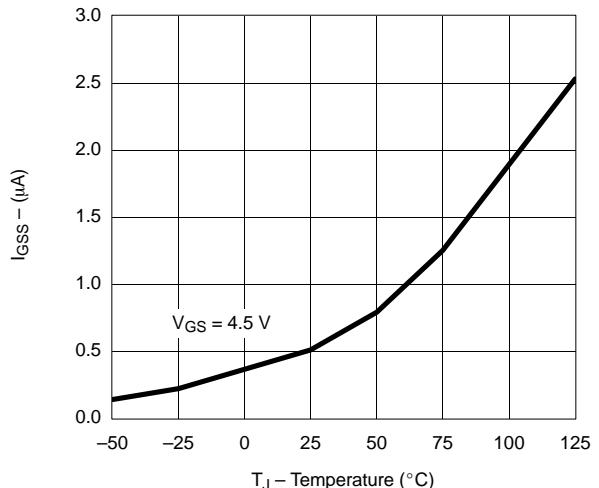
On-Resistance vs. Gate-to-Source Voltage



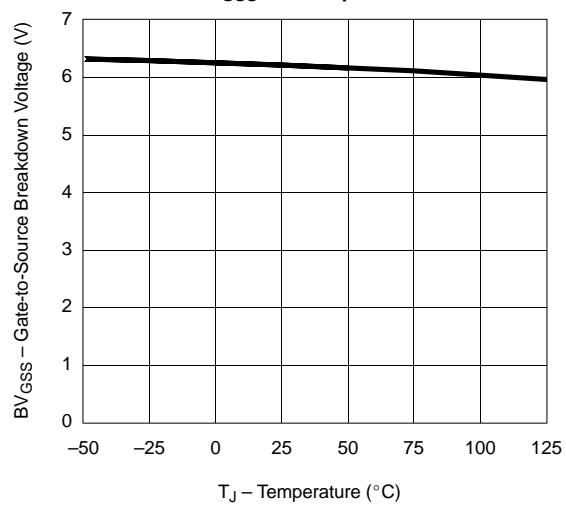
Threshold Voltage Variance vs. Temperature



I_{GSS} vs. Temperature



BV_{GSS} vs. Temperature





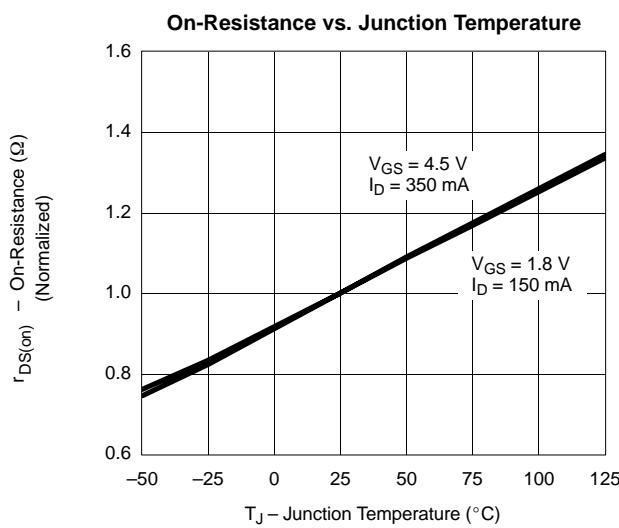
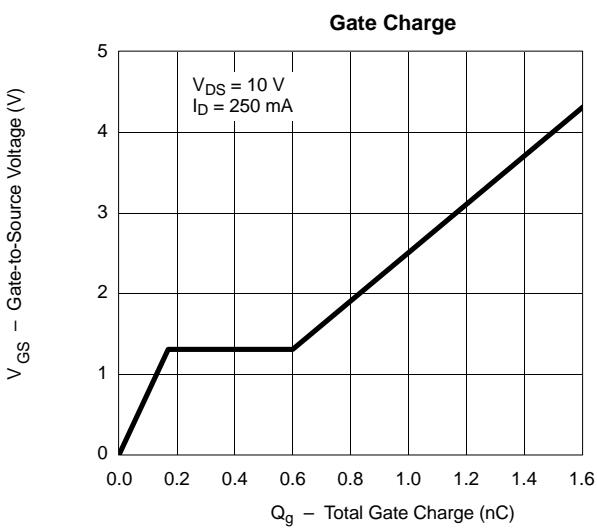
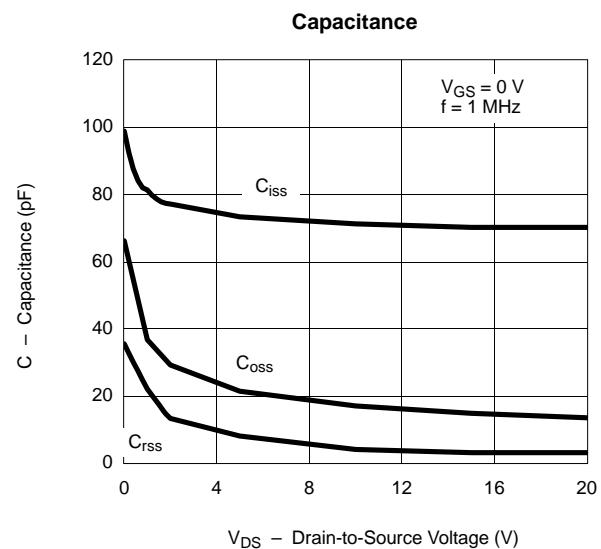
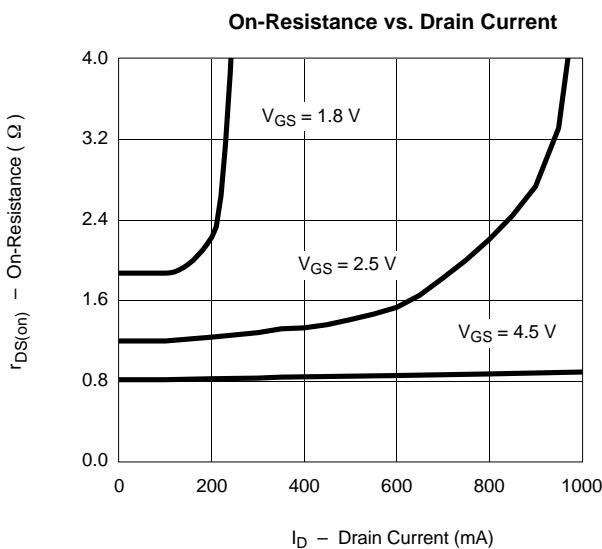
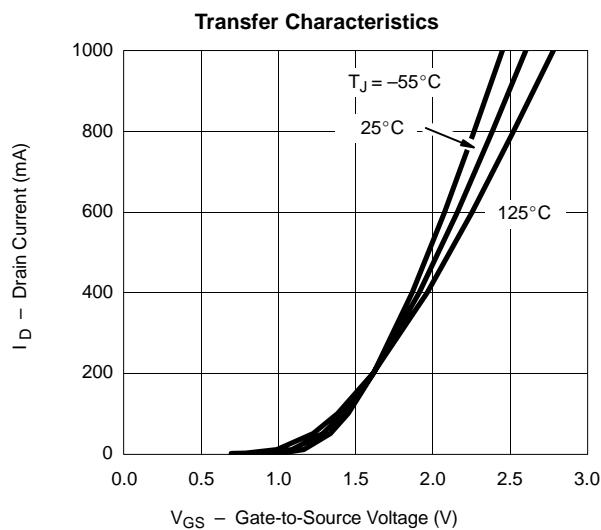
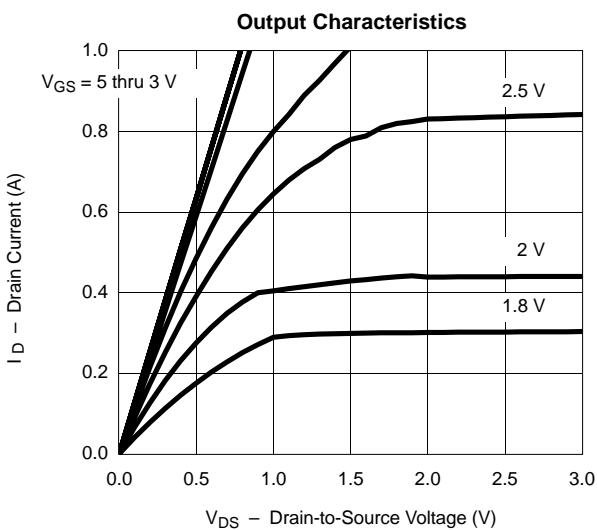
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TYPICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ UNLESS NOTED)

P-CHANNEL



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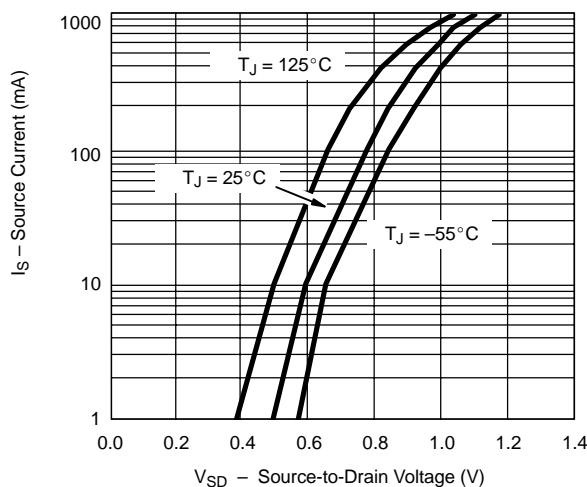
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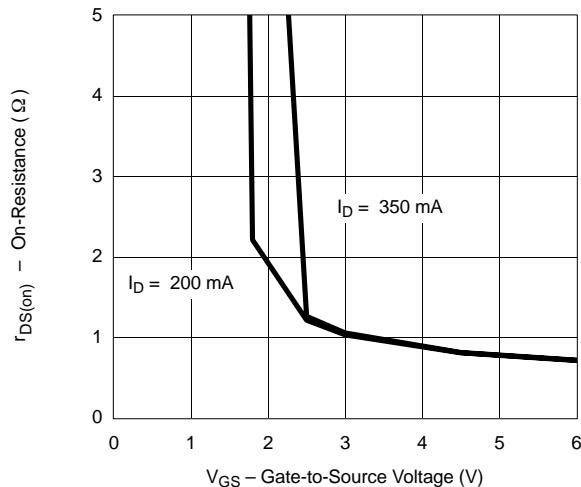
TYPICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ UNLESS NOTED)

P-CHANNEL

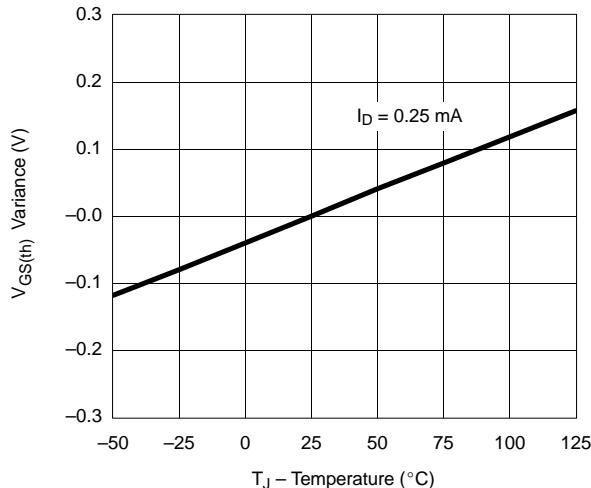
Source-Drain Diode Forward Voltage



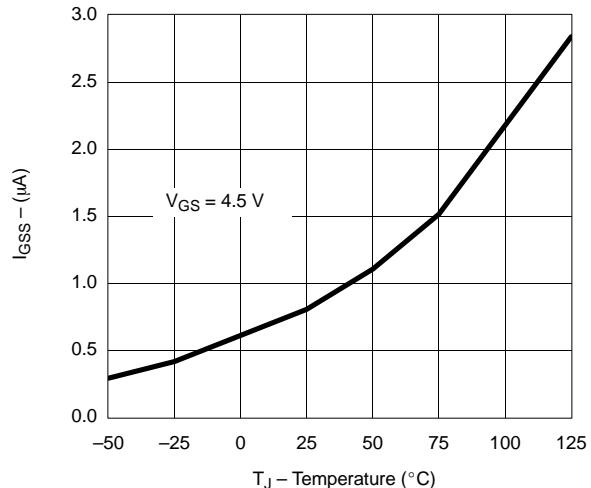
On-Resistance vs. Gate-to-Source Voltage



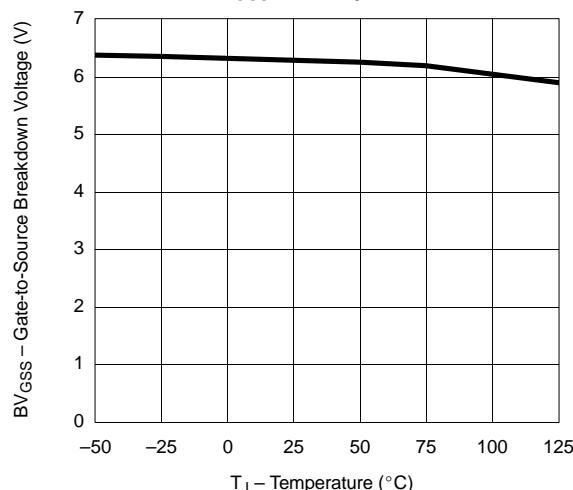
Threshold Voltage Variance vs. Temperature



I_{GSS} vs. Temperature



BV_{GSS} vs. Temperature





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TYPICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ UNLESS NOTED)

N- OR P-CHANNEL

Normalized Thermal Transient Impedance, Junction-to-Ambient

